

COM Express Compact size Type 6 Module, 6th Generation Intel® Core™ ULT Processor, DDR4, VGA, LVDS, DDI, GbE, SATA 6Gb/s, USB 3.2 Gen 1 (5Gb/s) and HD Audio, RoHS

Dual-channel DDR4 2133/1867 MHz



On-board eMMC 5.0 (optional)



One piece heat sink for COM **Express Basic Size provides** better thermal solution













Specifications

6th generation Intel® mobile ULT on-board SoC Intel® Core™ i7-6600U (up to 3.4GHz, dual-core, 4MB cache, TDP=15W) Intel® Core™ i3-6100U (up to 2.3GHz, dual-core, 3MB cache, TDP=15W) Intel® Celeron® processor 3955U (up to 2.0GHz, dual-core, 2MB cache, TDP=15W) Intel® Celeron® processor 3855U (up to 1.6GHz, dual-core, 2MB cache, TDP=15W)

Two 260-pin 2133/1866 MHz dual-channel DDR4 non-ECC unbuffered SO-DIMMs support up to 32GB

♦ BIOS

UEFI BIOS

♦ Graphic Engine

Intel® HD Graphics Gen 9 support for DX11/12, OCL 2.x, OGL 4.3/4.4, ES 2.0 Decode/Encode for HEVC, VP8, VP9 2 ,VDENC

◆ Display Output

1 x DDI: DisplayPort/HDMI/DVI (up to 3840x2160@60Hz)

1 x DDI: DP to VGA via CH7517

(1 x Optional DisplayPort / HDMI/DVI up to 1920x1200@60Hz)

1 x DDI: Embedded DP (up to 3840x2160@60Hz)

(Option with 1 x Dual Channel LVDS 18/24 bit via CH7511B) (up to 1920x1200@60Hz)

◆ Ethernet

Intel® Clarkville-V I219LM Support Intel® AMT 11.0

♦ I/O Interface

2 x RS-232 (2-Wire) to base board

4 x USB 2.0 to base board 4 x USB 3.2 Gen 1 (5Gb/s) to base board (with 4 x USB 2.0)

2 x SATA 6Gb/s signal to base board

◆ Audio

High definition audio interface ◆ SMBus

YES, to base board

♦ I²C

YES, to base board ◆ LPC

YES, to base board

◆ Expansion

1 x PCle x1 signal to base board (Via PCle x16 channel)

8 x PCIe x1 signal to base board

♦ Watchdog Timer

Software programmable, supports 1~255 sec. system reset

◆ eMMC

eMMC 5.0 (optional)

♦ GPIO

8 bit GPIO, to base board

◆ TPM

Through base board

 Power Supply 12V: 12V±5%, 5VSB: 5V±5%, RTC Battery: 2.0-3.3V ◆ Power Consumption

+12V@2.57A, 5VSB@0.04A, 5V@0.02A (Intel® Core™ i7-6600U with two 8GB 2400 MHz DDR4 memory)

◆ Operating Temperature -20°C ~ 65°C Operating Humidity

5% ~ 95%, non-condensing ◆ Diemension

95 mm x 95 mm

♦ Weight

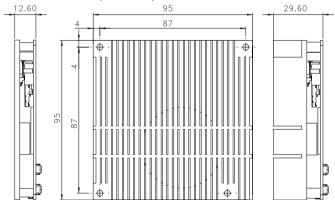
GW: 600g / NW: 250g

♦ CE/FCC compliant

Features

- Intel® Skylake ULT Processors supported
- Intel® HD Graphics technology integrates high-performance graphics and media
- Two 260-pin 2133/1867 MHz Dual-Channel DDR4 SDRAM Unbuffered DIMM supported (system max. 32GB)
- 18/24-bit dual-channel LVDS, analog CRT, DDI supported
- Support Intel® AMT 11.0

Dimensions (Unit: mm)



Packing List

1 x ICE-ULT3 single board computer	
1 x Heatsink	1 x QIG

Ordering Information

Part No.	Description
ICE-ULT3-i7-R10	COM Express Compact size Type 6 Module, 6th Generation Intel® Core™ i7-6600U (15W) on-board Processor (ULT), DDR4, VGA, LVDS, DDI, GbE, USB 3.2 Gen 1 (5Gb/s), SATA 6Gb/s and HD Audio, RoHS
ICE-ULT3-i3-R10	COM Express Compact size Type 6 Module, 6th Generation Intel® Core™ i3-6100U (15W) on-board Processor (ULT), DDR4, VGA, LVDS, DDI, GbE, USB 3.2 Gen 1 (5Gb/s), SATA 6Gb/s and HD Audio, RoHS
ICE-ULT3-C-R10	COM Express Compact size Type 6 Module, Intel® Celeron® 3955U (15W) on-board Processor (ULT), DDR4, VGA, LVDS, DDI, GbE, USB 3.2 Gen 1 (5Gb/s), SATA 6Gb/s and HD Audio, RoHS
ICE-ULT3-CE-R10	COM Express Compact size Type 6 Module, Intel® Celeron® 3855U (15W) on-board Processor (ULT), DDR4, VGA, LVDS, DDI, GbE, USB 3.2 Gen 1 (5Gb/s), SATA 6Gb/s and HD Audio, RoHS
ICE-DB-T6R-R11	Base Board for COM Express Type 6 Module COM.0 Rev. 2.1, support PICMG EAPI R1.0

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

IEI:

ICE-ULT3-i3-R10 ICE-ULT3-i5-R10 ICE-ULT3-i7-R10 ICE-ULT3-C-R10 ICE-ULT3-CE-R10